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Part Number: [73770-1309](#)
Status: **Active**
Overview: HDM®
Description: HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

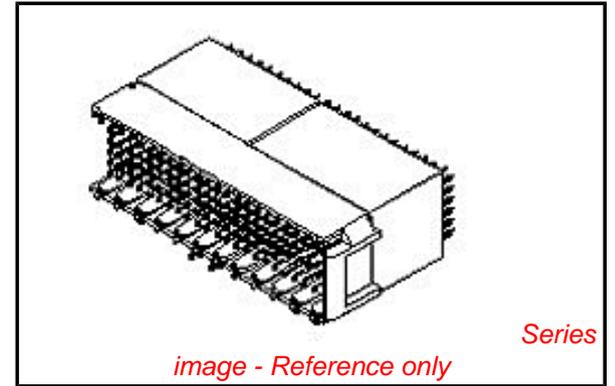
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73770](#)
 Application Backplane, Mezzanine
 Comments Closed End Option
 Component Type PCB Header
 Overview [HDM®](#)
 Product Name HDM®
 Style N/A
 UPC 822350313292

Physical

Circuits (Loaded) 144
 Circuits (maximum) 144
 Color - Resin Black
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Number of Columns 24
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 0.381µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole - Compliant Pin



EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Not Reviewed**
**Low-Halogen Status
 Not Reviewed**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of
 Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
 non-product compliance questions.

Search Parts in this Series

[73770Series](#)

Mates With

73632 HDM PLUS® Board-to-Board
 Daughtercard Receptacle. 73780 HDM®
 Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
 found by selecting the products below.
 Crimp Height Specifications are then
 contained in the Application Tooling
 Specification document.*

Global

Description	Product #
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	
Extraction Tool	0621001000

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info**Reference - Drawing Numbers**

Product Specification	PS-73780-999
Sales Drawing	SD-73770-002

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